

## 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

## Notification# 20170614005 Datasheet for TL16C752D-Q1 Information Only

**Date:** June 27, 2017

To: PREMIER FARNELL PCN

#### Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

# Information Only Attachments

### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

**DEVICE** TL16C752DPFBRQ1

**CUSTOMER PART NUMBER** 

null

Technical details of this Product Change follow on the next page(s).

Title: Datasheet for TL16C752D-Q1  Customer Contact: PCN Manager Dept: Quality Services  Change Type:  □ Assembly Site □ Design □ Wafer Bump Site □ Masembly Process □ Data Sheet □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Process □ Mechanical Specification □ Test Site □ Wafer Fab Materials □ Wafer Fab Site □ Wafer Fab Process □ Wafer Fab Naterials □ Wafer Fab Process □ Wafer Fab Process ■ □ Wafer Fab Naterials □ Wafer Fab Process ■ □ Wafer Fab Vite Fab Process ■ □ Wafer Fab Proces ■ □ Wafer Fab Process ■ □ Wafer Fab Process ■ □ Wafer Fab Proces				-1									
Customer Contact: PCN Manager Dept: Quality Services  Change Type:  Assembly Site Data Sheet Wafer Bump Site  Assembly Process Data Sheet Wafer Bump Material  Assembly Materials Part number change Wafer Bump Process  Mechanical Specification Test Site Wafer Fab Site  Packing/Shipping/Labeling Test Process Wafer Fab Materials  Wafer Fab Materials  Notification Details  Description of Change:  Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.  **TEXAS**  I L16C752D-Q1**  SLLSET4B - FEBRUARY 2016-REVISED JANUARY 2017  Changes from Revision A (March 2016) to Revision B Page  • Changed pins 9, 10, and 11 to active low in the Pin Configurations and Function image	<b>PCN Number</b>		er:	20	0170614	1005	5	<b>PCN Date:</b>	Ju	June 27, 20		)17	
Change Type:  Assembly Site  Assembly Process  Assembly Materials  Wafer Bump Material  Wafer Bump Materials  Wafer Bump Material  Wafer Bump Materials  Wafer Bump Material  Wafer Bump Material  Wafer Bump Material  Wafer Bump Process  Wafer Bump Materials  Wafer Bump Process  Nafer Bump Process  Nafer Bump Process  Nafer Bump Process  Nafer Bump Proces  Nafer Bump Process  Nafer Bu	Title	Title: Datasheet for TL16C752D-Q1											
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Assembly Process Assembly Materials Wafer Fab Site Wafer Fab Materials Wafer Pab Materials Wafer Pab Materials Wafer Pab	Chan	nge Ty	pe:										
Assembly Materials		Assem	bly Site		•		Design			Wafer Bump Site			
Mechanical Specification		Assem	bly Process			$\boxtimes$				Wafer Bump Material			
Packing/Shipping/Labeling   Test Process   Wafer Fab Materials   Wafer Fab Process							Part number change				Wafer Bump Process		
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	Prod	luct A	ffected:										
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com